

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>EMRE ALPTEKIN</td> <td>01/24/2014</td> </tr> <tr> <td>POOJA R. BATRA</td> <td>01/20/2014</td> </tr> <tr> <td>KANGGUO CHENG</td> <td>02/14/2014</td> </tr> <tr> <td>RAMACHANDRA DIVAKARUNI</td> <td>02/11/2014</td> </tr> <tr> <td>JOHNATHAN E. FALTERMEIER</td> <td>02/03/2014</td> </tr> <tr> <td>REINALDO A. VEGA</td> <td>01/16/2014</td> </tr> </tbody> </table>		Name	Execution Date	EMRE ALPTEKIN	01/24/2014	POOJA R. BATRA	01/20/2014	KANGGUO CHENG	02/14/2014	RAMACHANDRA DIVAKARUNI	02/11/2014	JOHNATHAN E. FALTERMEIER	02/03/2014	REINALDO A. VEGA	01/16/2014
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REINALDO A. VEGA	01/16/2014														
RECEIVING PARTY DATA															
Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION														
Street Address:	NEW ORCHARD ROAD														
City:	ARMONK														
State/Country:	NEW YORK														
Postal Code:	10504														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14184756</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14184756										
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Application Number:	14184756														
CORRESPONDENCE DATA															
Fax Number:	(607)429-4119														
Phone:	845-894-4279														
Email:	johnsodc@us.ibm.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	IBM CORP - ENDICOTT DRAFTING CENTER														
Address Line 1:	2070 ROUTE 52														
Address Line 4:	HOPEWELL JUNCTION, NEW YORK 12533														
ATTORNEY DOCKET NUMBER:	FIS920130228US1														
NAME OF SUBMITTER:	TRENTICE V. BOLAR														

PATENT

Signature:	/Trentice V. Bolar/
Date:	02/20/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 18 source=FIS920130228US1_Executed_Declaration#page1.tif source=FIS920130228US1_Executed_Declaration#page2.tif source=FIS920130228US1_Executed_Declaration#page3.tif source=FIS920130228US1_Executed_Declaration#page4.tif source=FIS920130228US1_Executed_Declaration#page5.tif source=FIS920130228US1_Executed_Declaration#page6.tif source=FIS920130228US1_Executed_Declaration#page7.tif source=FIS920130228US1_Executed_Declaration#page8.tif source=FIS920130228US1_Executed_Declaration#page9.tif source=FIS920130228US1_Executed_Declaration#page10.tif source=FIS920130228US1_Executed_Declaration#page11.tif source=FIS920130228US1_Executed_Declaration#page12.tif source=FIS920130228US1_Executed_Declaration#page13.tif source=FIS920130228US1_Executed_Declaration#page14.tif source=FIS920130228US1_Executed_Declaration#page15.tif source=FIS920130228US1_Executed_Declaration#page16.tif source=FIS920130228US1_Executed_Declaration#page17.tif source=FIS920130228US1_Executed_Declaration#page18.tif	

DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT

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Whereas, International Business Machines Corporation (herein referred to as the "ASSIGNEE"), a corporation of New York having a place of business at Armonk, New York, desires to acquire, and I desire to grant to the ASSIGNEE, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the ASSIGNEE, its successors, legal representatives, and assigns, whenever requested by the ASSIGNEE, its successors, legal representatives, or assigns.

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(1) Legal Name of Inventor: **Emre Alptekin**

Signature:  Date: 01/24/2014

(2) Legal Name of Inventor: **Pooja R. Batra**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Kangua Cheng**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Ramachandra Divakaruni**

Signature: _____ Date: _____

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Signature: _____ Date: _____

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Signature: _____ Date: _____

(2) Legal Name of Inventor: **Pooja R. Batra**

Signature: Pooja _____ Date: 01/20/2014

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Signature: _____ Date: _____

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Kangguo

F.C

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Signature:  Date: 2/14/2014

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Signature: _____ Date: _____

(4) Legal Name of Inventor: **Ramachandra Divakaruni**

Signature: Ramachandra Divakaruni Date: Feb 11, 2014
(R.D.)

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Signature: Reinaldo Vega Date: 1/16/14